MOSFET - Dual, N-Channel, Small Signal, ESD **Protection, SC-88** 20 V

Features

- Small Footprint (2 x 2 mm)
- Low Gate Charge N-Channel Device
- ESD Protected Gate
- Same Package as SC-70 (6 Leads)
- AEC-Q101 Qualified and PPAP Capable NVJD4401N
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Load Power Switching
- Li-Ion Battery Supplied Devices
- Cell Phones, Media Players, Digital Cameras, PDAs
- DC-DC Conversion

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

| Parame | Symbol | Value | Unit | | |
|---|-----------------------------------|-----------------------|-----------------|------|----|
| Drain-to-Source Voltage | V_{DSS} | 20 | V | | |
| Gate-to-Source Voltage | | | V_{GS} | ±12 | V |
| Continuous Drain Current | Steady State | T _A = 25°C | I _D | 0.63 | Α |
| (Based on R _{θJA}) | State | T _A = 85°C | | 0.46 | |
| Power Dissipation | Steady State | T _A = 25°C | P _D | 0.27 | W |
| (Based on R _{θJA}) | State | T _A = 85°C | | 0.14 | |
| Continuous Drain Current | Steady State | T _A = 25°C | I _D | 0.91 | Α |
| (Based on R _{θJL}) | State | T _A = 85°C | | 0.65 | |
| Power Dissipation | Steady | T _A = 25°C | | 0.55 | W |
| (Based on R _{θJL}) | State | T _A = 85°C | P_{D} | 0.29 | |
| Pulsed Drain Current | | t ≤10 μs | I _{DM} | ±1.2 | Α |
| Operating Junction and S | T _J , T _{STG} | –55 to 150 | °C | | |
| Continuous Source Current (Body Diode) | | | I _S | 0.63 | Α |
| Lead Temperature for So (1/8" from case for 10 s) | oldering P | urposes | T_L | 260 | °C |

THERMAL RESISTANCE RATINGS (Note 1)

| Parameter | Symbol | Тур | Max | Units |
|---|-----------------|-----|-----|-------|
| Junction-to-Ambient - Steady State | $R_{\theta JA}$ | 400 | 458 | °C/W |
| Junction-to-Lead (Drain) - Steady State | $R_{	heta JL}$ | 194 | 252 | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

1. Surface mounted on FR4 board using 1 oz Cu area = 0.9523 in sq.

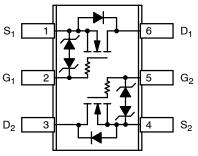


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| V _{(BR)DSS} | R _{DS(on)} Typ | I _D Max |
|----------------------|-------------------------|--------------------|
| 20 V | 0.29 Ω @ 4.5 V | 0.63 A |
| 20 V | 0.36 Ω @ 2.5 V | 0.03 A |

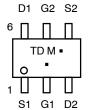
SC-88 (SOT-363)



Top View

MARKING DIAGRAM & PIN ASSIGNMENT





TD = Device Code M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

| Parameter | Symbol | Test Con | dition | Min | Тур | Max | Unit |
|--|--------------------------------------|---|---------------------------|-----|-------|-------|--------|
| OFF CHARACTERISTICS | | | • | | • | | • |
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0 \text{ V, } I_{D}$ |) = 250 μΑ | 20 | 27 | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} /T _J | | | | 22 | | mV/ °C |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{GS} = 0 V, V | _{DS} = 16 V | | | 1.0 | μΑ |
| Gate-to-Source Leakage Current | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{C}$ | _{GS} = ±12 V | | | 10 | μА |
| ON CHARACTERISTICS (Note 2) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | $V_{GS} = V_{DS}, I_{DS}$ | _O = 250 μA | 0.6 | 0.92 | 1.5 | V |
| Gate Threshold Temperature Coefficient | V _{GS(TH)} /T _J | | | | -2.1 | | mV/ °C |
| Drain-to-Source On Resistance | R _{DS(on)} | V _{GS} = 4.5 V, I | _D = 0.63 A | | 0.29 | 0.375 | Ω |
| | | V _{GS} = 2.5 V, I _D = 0.40 A | | | 0.36 | 0.445 | |
| Forward Transconductance | 9FS | V _{DS} = 4.0 V, I _D = 0.63 A | | | 2.0 | | S |
| CHARGES AND CAPACITANCES | | | | | | | |
| Input Capacitance | C _{ISS} | $V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$ | | | 33 | 46 | pF |
| Output Capacitance | Coss | | | | 13 | 22 | |
| Reverse Transfer Capacitance | C _{RSS} | | | | 2.8 | 5.0 | |
| Total Gate Charge | Q _{G(TOT)} | | | | 1.3 | 3.0 | nC |
| Threshold Gate Charge | Q _{G(TH)} | V _{GS} = 4.5 V, V | / _{DS} = 10 V, | | 0.1 | | |
| Gate-to-Source Charge | Q _{GS} | I _D = 0.6 | 63 A | | 0.2 | | |
| Gate-to-Drain Charge | Q_{GD} | | Ī | | 0.4 | | |
| SWITCHING CHARACTERISTICS (No | ote 3) | | | | | | |
| Turn-On Delay Time | td _(ON) | | | | 0.083 | | μS |
| Rise Time | tr | V _{GS} = 4.5 V, V | _{'DD} = 10 V, | | 0.227 | | 1 |
| Turn-Off Delay Time | td _(OFF) | I _D = 0.5 A, F | $R_{\rm G} = 20 \ \Omega$ | | 0.786 | | 1 |
| Fall Time | tf | | | | 0.506 | | |
| DRAIN-SOURCE DIODE CHARACTE | RISTICS | | • | | • | - | |
| Forward Diode Voltage | V _{SD} | $V_{GS} = 0 V$, | T _J = 25°C | | 0.76 | 1.1 | V |
| | | I _S =0.23 A | T _J = 125°C | | 0.63 | | 1 |
| Reverse Recovery Time | t _{RR} | $V_{GS} = 0 \text{ V, } dI_{S}/dt$ $I_{S} = 0.6$ | | | 0.410 | | μs |

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

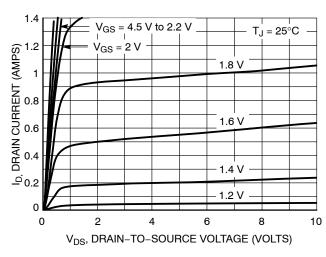


Figure 1. On-Region Characteristics

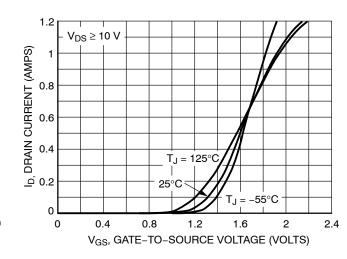


Figure 2. Transfer Characteristics

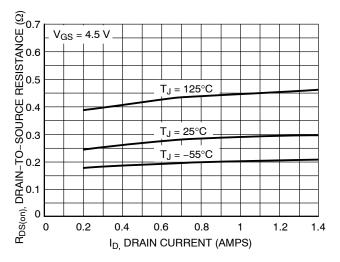


Figure 3. On-Resistance vs. Drain Current and Temperature

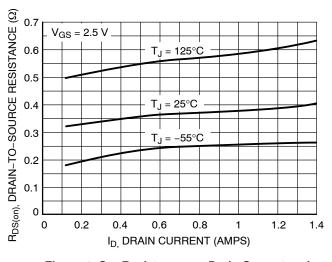


Figure 4. On-Resistance vs. Drain Current and Temperature

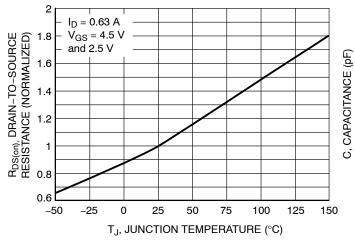


Figure 5. On–Resistance Variation with Temperature

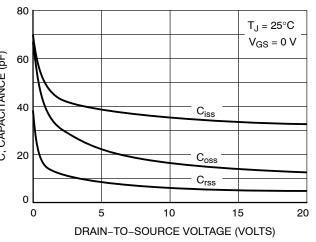


Figure 6. Capacitance Variation

$\textbf{TYPICAL PERFORMANCE CURVES} \ (T_J = 25^{\circ}\text{C unless otherwise noted})$

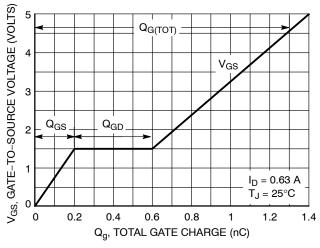


Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

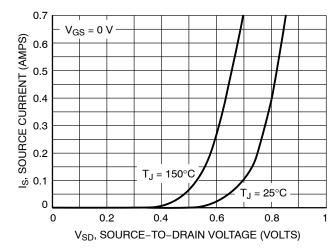


Figure 8. Diode Forward Voltage vs. Current

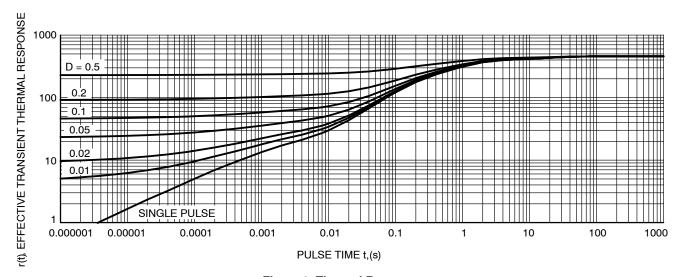


Figure 9. Thermal Response

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|--------------------|-----------------------|
| NTJD4401NT1G | SC-88 (Pb-Free) | 3000 / Tape & Reel |
| NVJD4401NT1G | SC-88 (Pb-Free) | 3000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

DATE 11 DEC 2012





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.

- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

| | MIL | LIMETE | ERS | | INCHES | } |
|-----|----------|----------|------|-------|----------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | | | 1.10 | | | 0.043 |
| A1 | 0.00 | | 0.10 | 0.000 | | 0.004 |
| A2 | 0.70 | 0.90 | 1.00 | 0.027 | 0.035 | 0.039 |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| С | 0.08 | 0.15 | 0.22 | 0.003 | 0.006 | 0.009 |
| D | 1.80 | 2.00 | 2.20 | 0.070 | 0.078 | 0.086 |
| E | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 |
| E1 | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| е | 0.65 BSC | | | 0 | .026 BS | С |
| L | 0.26 | 0.36 | 0.46 | 0.010 | 0.014 | 0.018 |
| L2 | | 0.15 BSC | | | 0.006 BS | SC |
| aaa | 0.15 | | | | 0.006 | |
| bbb | 0.30 | | | | 0.012 | |
| ccc | 0.10 | | | | 0.004 | |
| ddd | | 0.10 | | | 0.004 | |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

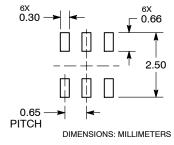
= Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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| STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2 | STYLE 2: CANCELLED | STYLE 3: CANCELLED | STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE | STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE | STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2 |
|--|--|---|---|---|--|
| STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2 | STYLE 8: CANCELLED | STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2 | STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2 | STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2 | STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2 |
| STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE | STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC | STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1 | STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1 | STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1 | STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1 |
| STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF | STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR | STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1 | STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c) | STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C | STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE |
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Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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